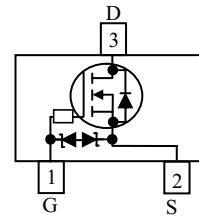


WNM2030
Single N-Channel, 20V, 0.95A, Power MOSFET
[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

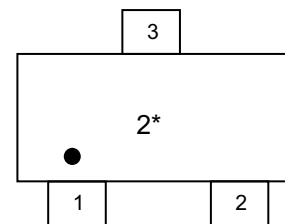
V _{DS} (V)	R _{ds(on)} (Ω)
20	0.210@ V _{GS} =4.5V
	0.250@ V _{GS} =2.5V
	0.305@ V _{GS} =1.8V
ESD Protected	


SOT-723
Descriptions

The WNM2030 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent R_{DS(ON)} with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNM2030 is Pb-free.


Pin configuration (Top view)
Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- Small package SOT-723



2 = Device Code
* = Month (A~Z)

Marking
Applications

- Driver for Relay, Solenoid, Motor, LED etc.
- DC-DC converter circuit
- Power Switch
- Load Switch
- Charging

Order information

Device	Package	Shipping
WNM2030-3/TR	SOT-723	8000/Reel&Tape

Absolute Maximum ratings

Parameter		Symbol	10 S	Steady State	Unit
Drain-Source Voltage		V_{DS}	20		V
Gate-Source Voltage		V_{GS}	± 6		
Continuous Drain Current ^a	$T_A=25^\circ\text{C}$	I_D	0.95	0.88	A
	$T_A=70^\circ\text{C}$		0.76	0.71	
Maximum Power Dissipation ^a	$T_A=25^\circ\text{C}$	P_D	0.43	0.37	W
	$T_A=70^\circ\text{C}$		0.28	0.24	
Continuous Drain Current ^b	$T_A=25^\circ\text{C}$	I_D	0.80	0.75	A
	$T_A=70^\circ\text{C}$		0.64	0.60	
Maximum Power Dissipation ^b	$T_A=25^\circ\text{C}$	P_D	0.31	0.27	W
	$T_A=70^\circ\text{C}$		0.20	0.17	
Pulsed Drain Current ^c		I_{DM}	1.5		A
Operating Junction Temperature		T_J	150		$^\circ\text{C}$
Lead Temperature		T_L	260		$^\circ\text{C}$
Storage Temperature Range		T_{stg}	-55 to 150		$^\circ\text{C}$

Thermal resistance ratings

Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance ^a	$t \leq 10 \text{ s}$	$R_{\theta JA}$	225	285	$^\circ\text{C/W}$
	Steady State		270	330	
Junction-to-Ambient Thermal Resistance ^b	$t \leq 10 \text{ s}$	$R_{\theta JA}$	330	400	
	Steady State		390	460	
Junction-to-Case Thermal Resistance		$R_{\theta JC}$	230	265	

a Surface mounted on FR-4 Board using 1 square inch pad size, 1oz copper

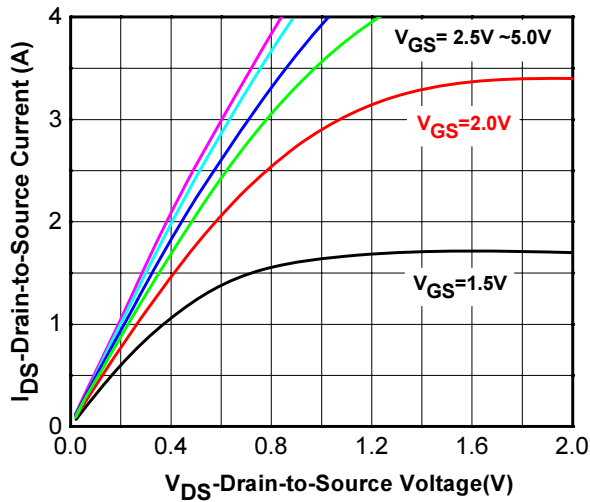
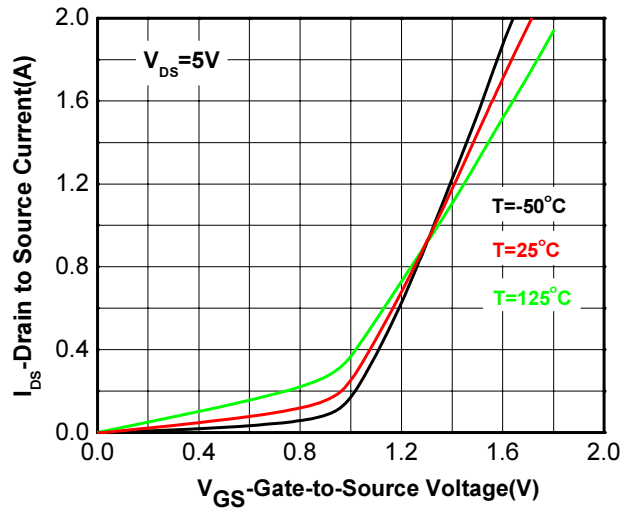
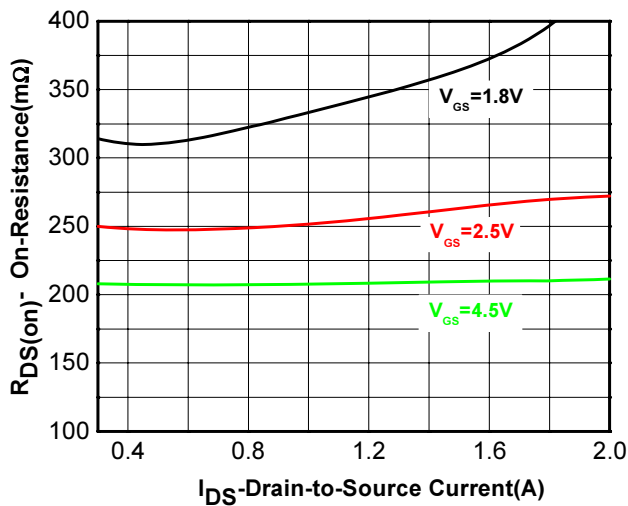
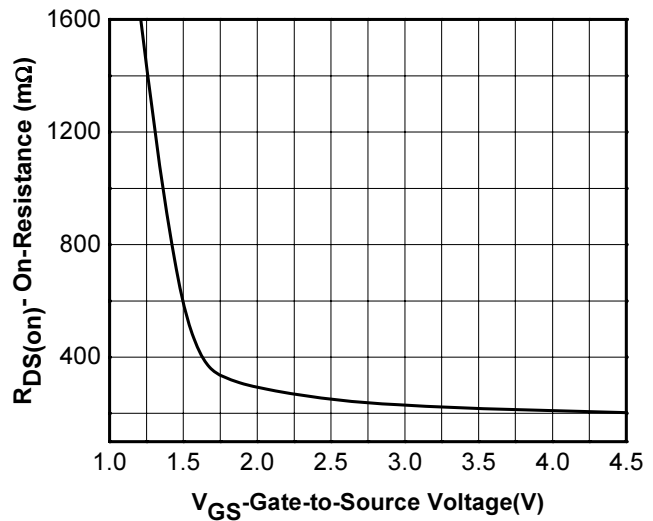
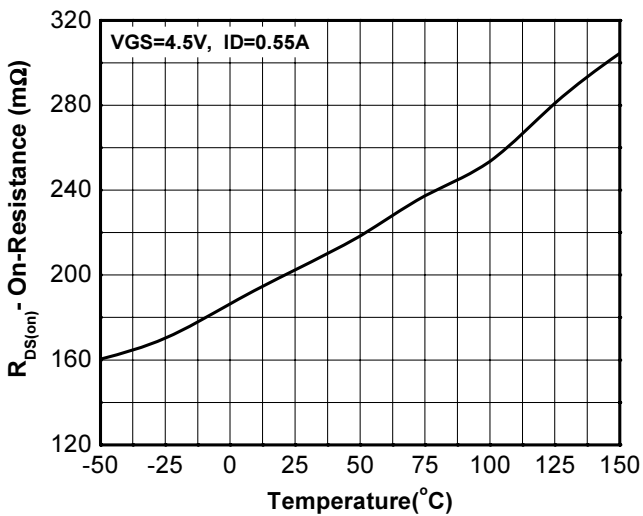
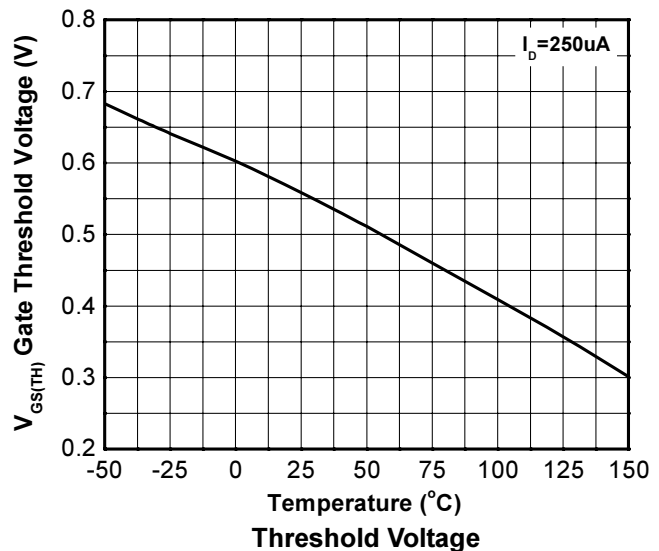
b Surface mounted on FR-4 board using minimum pad size, 1oz copper

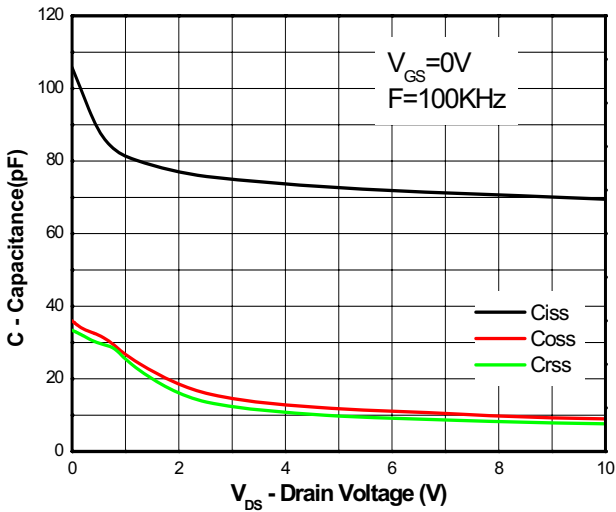
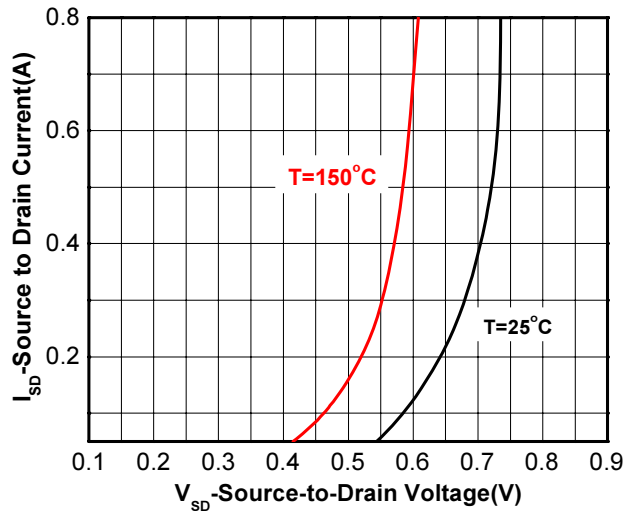
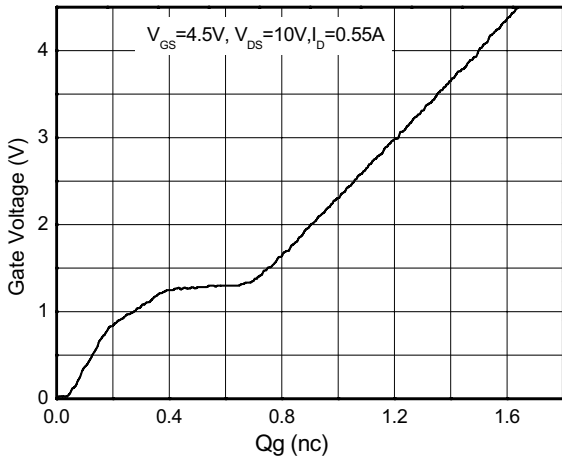
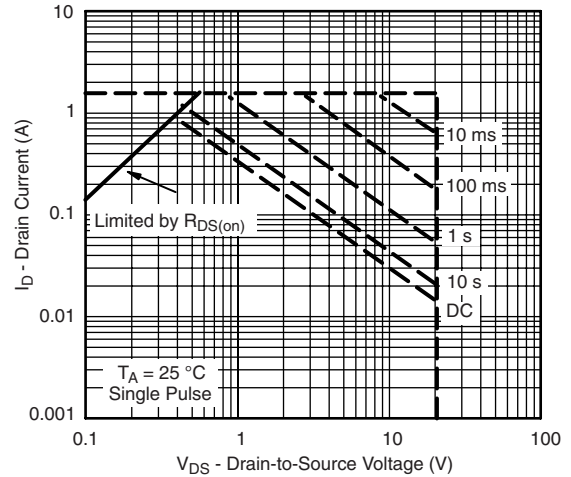
c Pulse width < 380 μs , Duty Cycle < 2%

d Maximum junction temperature $T_J=150^\circ\text{C}$.

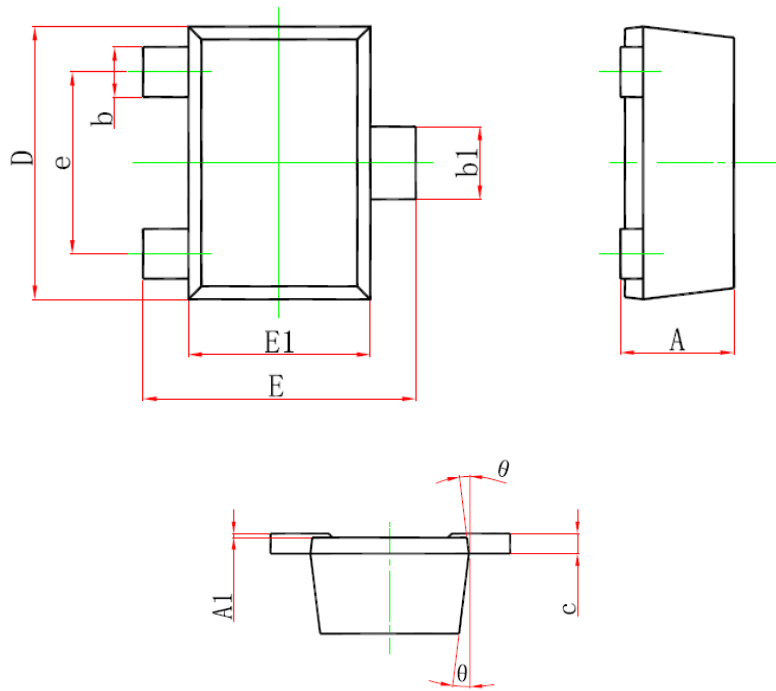
Electronics Characteristics (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0\text{ V}, I_D = 250\mu\text{A}$	20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 16\text{V}, V_{GS} = 0\text{V}$			1	μA
Gate-to-source Leakage Current	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 5\text{V}$			± 5	μA
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	0.45	0.65	1.0	V
Drain-to-source On-resistance ^{b, c}	$R_{DS(on)}$	$V_{GS} = 4.5\text{V}, I_D = 0.55\text{A}$		210	310	m Ω
		$V_{GS} = 2.5\text{V}, I_D = 0.50\text{A}$		250	360	
		$V_{GS} = 1.8\text{V}, I_D = 0.35\text{A}$		305	460	
CAPACITANCES, CHARGES						
Input Capacitance	C_{ISS}	$V_{GS} = 0\text{ V},$ $f = 100\text{KHz},$ $V_{DS} = 10\text{ V}$		50		pF
Output Capacitance	C_{OSS}			13		
Reverse Transfer Capacitance	C_{RSS}			8		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5\text{ V},$ $V_{DS} = 10\text{ V},$ $I_D = 0.55\text{A}$		1.15		nC
Threshold Gate Charge	$Q_{G(TH)}$			0.06		
Gate-to-Source Charge	Q_{GS}			0.15		
Gate-to-Drain Charge	Q_{GD}			0.23		
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	$t_d(ON)$	$V_{GS} = 4.5\text{ V},$ $V_{DD} = 10\text{ V},$ $I_D = 0.55\text{ A},$ $R_G = 6\ \Omega$		22		ns
Rise Time	t_r			80		
Turn-Off Delay Time	$t_d(OFF)$			700		
Fall Time	t_f			380		
BODY DIODE CHARACTERISTICS						
Forward Voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_S = 0.35\text{A}$	0.5	0.7	1.5	V

Typical Characteristics (Ta=25°C, unless otherwise noted)

Output Characteristics

Transfer Characteristics

On Resistance vs. Drain Current

On Resistance vs. V_{GS} vs. Temperature

On Resistance vs. Junction Temperature

Threshold Voltage


Capacitance

Body diode forward voltage

Gate Charge Characteristics

Safe operating power

Transient thermal response (Junction-to-Ambient)

Package outline dimensions
SOT-723


Symbol	Dimension in Millimeters	
	Min.	Max.
A		0.550
A1	0.000	0.050
b	0.170	0.270
b1	0.270	0.370
c		0.180
D	1.150	1.250
E	1.150	1.250
E1	0.750	0.850
e	0.800 TYP	
θ	7° REF.	